

PATENT ASSIGNMENT COVER SHEET

Electronic Version v1.1
 Stylesheet Version v1.2

EPAS ID: PAT6171082

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT

CONVEYING PARTY DATA

Name	Execution Date
FENGCHUN XIE	10/10/2019
YINGCONG DENG	10/22/2019
YUN LIU	10/22/2019
DANDAN ZHANG	10/10/2019
LVHAI HU	10/20/2019
ROBERTO FRANCISCO-YI LU	10/10/2019
QINGLONG ZENG	10/22/2019
LAN GONG	10/14/2019
QIAN YING	10/10/2019

RECEIVING PARTY DATA

Name:	TYCO ELECTRONICS (SHANGHAI) CO. LTD.
Street Address:	SECTIONS F, G, H, LEVEL 1, BUILDING 15
Internal Address:	NO. 999 YINGLUN ROAD, CHINA (SHANGHAI) PILOT FREE TRADE ZONE
City:	SHANGHAI
State/Country:	CHINA
Name:	TE CONNECTIVITY SERVICES GMBH
Street Address:	RHEINSTRASSE 20
City:	SCHAFFHAUSEN
State/Country:	SWITZERLAND
Postal Code:	8200
Name:	MEASUREMENT SPECIALTIES (CHENGDU) LTD.
Street Address:	NO. 368 WULIANYI 1ST ROAD
Internal Address:	GONGXING TOWN, SHUANGLIU COUNTY, SICHUAN
City:	CHENDU
State/Country:	CHINA
Postal Code:	610200
Name:	SHENZHEN AMI TECHNOLOGY CO. LTD.
Street Address:	1/F, H2 BUILDING, HONGFA HI-TECH INDUSTRIAL PARK
Internal Address:	TANGTOU BLVD., SHIYAN, BAOAN DISTRICT
City:	SHENZHEN

PATENT

State/Country:

CHINA

PROPERTY NUMBERS Total: 1

Property Type	Number
Application Number:	16685462

CORRESPONDENCE DATA

Fax Number: (610)889-3696

Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.

Phone: 610-889-3699

Email: berwynipdocket@barley.com

Correspondent Name: BARLEY SNYDER

Address Line 1: 2 GREAT VALLEY PARKWAY

Address Line 2: SUITE 110

Address Line 4: MALVERN, PENNSYLVANIA 19355

ATTORNEY DOCKET NUMBER: 21334-2895

NAME OF SUBMITTER: SALVATORE ANASTASI

SIGNATURE: /Salvatore Anastasi/

DATE SIGNED: 06/25/2020

Total Attachments: 3

source=RevisedDeclaration#page1.tif

source=RevisedDeclaration#page2.tif

source=RevisedDeclaration#page3.tif

Barley Snyder Ref.: 21334-2895

COMBINED DECLARATION AND ASSIGNMENT

As a below-named inventor, I hereby declare that:

this declaration is directed to inventions and improvements disclosed in:

☒ the attached application, or

☐ United States application or PCT international application number _____ filed on _____, entitled Wire Automatic Soldering System ("the APPLICATION")

The APPLICATION was made or authorized to be made by me;

I believe that I am the original inventor or an original joint inventor of a claimed invention in the APPLICATION;

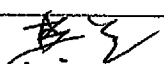

I have reviewed and understand the contents of the APPLICATION, including the claims, and I am aware of the duty to disclose to the United States Patent and Trademark Office all information known to me to be material to patentability as defined in 37.C.F.R 1.56; AND

I hereby acknowledge that any willful false statement made in this declaration is punishable under 18 U.S.C. 1001 by fine or imprisonment of not more than five (5) years, or both.

As a below named and signing inventor, acknowledging that I have assigned or have obligations to assign the APPLICATION to:

Tyco Electronics (Shanghai) Co. Ltd. and TE Connectivity Services GmbH and Measurement Specialties (Chengdu) Ltd. and Shenzhen AMI Technology Co., Ltd. ("ASSIGNEE"), corporations organized and existing under and by virtue of the laws of *China* and the *Switzerland* and having their principal place of business at *Sections F,G and H Level 1 Building 15, No. 999, Yinglun Road China (Shanghai), Pilot Free Trade Zone, Shanghai, China* and *Rheinstrasse 20, 8200 Schaffhausen, Switzerland*, and *No. 368 Wulianyi 1st/ Road, Gongxing Town, Shuangliu County, Chendu, Sichuan, 610200, China* and *1/F, H2 Bldg, Hongfa Hi-tech Industrial Park, Tangtou Blvd, Shiyan, Baoan District, Shenzhen, China*

for a valuable consideration, the receipt of which is hereby acknowledged, **I do hereby sell, assign, transfer and set over unto the said ASSIGNEE, its successors and assigns**, my full and entire right, title and interest in and to the APPLICATION, the inventions and improvements disclosed in the APPLICATION, all divisions, continuations, continuations-in-part, or renewals thereof, all Letters Patent to be granted and issued therefor, not only for, to and in the rights under the International Convention, and all reissues, re-examinations, renewals or extensions thereof, and I hereby authorize and request the United States Patent and Trademark Office and/or other patent office(s) to issue said Letters Patent to said ASSIGNEE, its successors and assigns, in accordance with this assignment

Legal Name	Signature	Date
XIE, Fengchun		
GONG, Lan		2019-10-14
YING, Qian		2019-10-10
DING, Yingcong		
LIU, Yun		
ZHANG, Dandan		
HU, Lvhai		

04-November-2019

Our Ref.: P194684.US.01

TE Ref.: TY-00703 US

Barley Snyder Ref.: 21334-2895

COMBINED DECLARATION AND ASSIGNMENT

As a below-named inventor, I hereby declare that:

this declaration is directed to inventions and improvements disclosed in:

☒ the attached application, or☐ United States application or PCT international application number _____ filed on _____, entitled Wire Automatic Soldering System ("the APPLICATION")

The APPLICATION was made or authorized to be made by me;

I believe that I am the original inventor or an original joint inventor of a claimed invention in the APPLICATION;

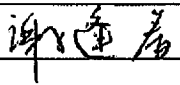
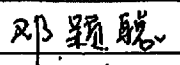
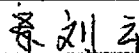
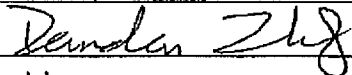

I have reviewed and understand the contents of the APPLICATION, including the claims, and I am aware of the duty to disclose to the United States Patent and Trademark Office all information known to me to be material to patentability as defined in 37.C.F.R. 1.56; AND

I hereby acknowledge that any willful false statement made in this declaration is punishable under 18 U.S.C. 1001 by fine or imprisonment of not more than five (5) years, or both.

As a below named and signing inventor, acknowledging that I have assigned or have obligations to assign the APPLICATION to:

Tyco Electronics (Shanghai) Co. Ltd. and TE Connectivity Services GmbH and Measurement Specialties (Chengdu) Ltd. and Shenzhen AMI Technology Co., Ltd. ("ASSIGNEE"), corporations organized and existing under and by virtue of the laws of *China* and the *Switzerland* and having their principal place of business at *Sections F,G and H Level 1 Building 15, No. 999, Yinglun Road China (Shanghai), Pilot Free Trade Zone, Shanghai, China* and *Rheinstrasse 20, 8200 Schaffhausen, Switzerland*, and *No. 368 Wulianyi 1st/ Road, Gongxing Town, Shuangliu County, Chendu, Sichuan, 610200, China* and *1/F, H2 Bldg, Hongfa Hi-tech Industrial Park, Tangtou Blvd, Shiyan, Baoan District, Shenzhen, China*

for a valuable consideration, the receipt of which is hereby acknowledged, I do hereby sell, assign, transfer and set over unto the said ASSIGNEE, its successors and assigns, my full and entire right, title and interest in and to the APPLICATION, the inventions and improvements disclosed in the APPLICATION, all divisions, continuations, continuations-in-part, or renewals thereof, all Letters Patent to be granted and issued therefor, not only for, to and in the rights under the International Convention, and all reissues, re-examinations, renewals or extensions thereof, and I hereby authorize and request the United States Patent and Trademark Office and/or other patent office(s) to issue said Letters Patent to said ASSIGNEE, its successors and assigns, in accordance with this assignment

Legal Name	Signature	Date
XIE, Fengchun		2019.10.10
GONG, Lan		
YING, Qian		
DING, Yingcong		2019.10.22.
LIU, Yun		2019.10.22.
ZHANG, Dandan		2019.10.10
HU, Lvhai		2019.10.20

04-November-2019

Our Ref.: P194684.US.01

TE Ref.: TY-00703 US

LU, Roberto Francisco-Yi	<i>Roberto F. Lu</i>	<i>2019.10.10</i>
ZENG, Qinglong	<i>Vernon Zeng</i>	<i>2019.10.22</i>